

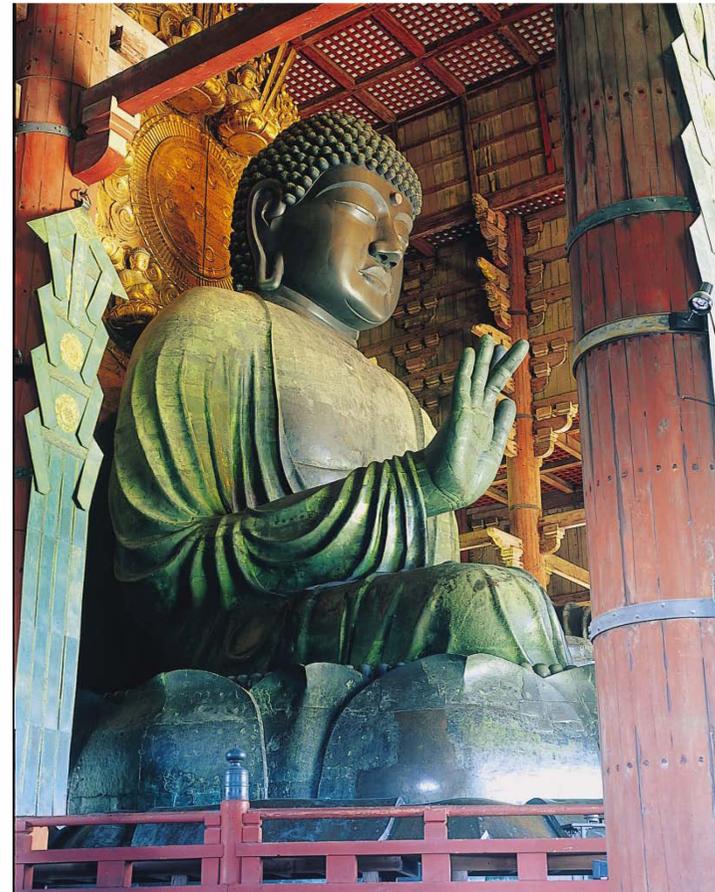
# Chair's Welcome



Welcome to the 9th International Workshop on Electromagnetic Compatibility of Integrated Circuits – EMC Compo 2013 in the "Historic Monuments of Ancient Nara", a UNESCO World Heritage Site. EMC Compo 2013 is the first workshop to be held outside Europe, and it's indeed a great honor for me as a General Chair to have this workshop in Japan with the cooperation of many people.

Another important feature of EMC Compo 2013 is that it is prepared and organized as a series Symposium/Workshop with the "2013 IEEE Electrical Design of Advanced Packaging & Systems Symposium (EDAPS 2013)", which is one of the IEEE CPMT Society Symposiums, chaired by Prof. Hideki Asai of Shizuoka University. Technical topics in EMC and Advanced Packaging are closely related and we share common issues and challenges to create new frontiers. I hope the attendees of both EDAPS and EMC Compo will have fruitful communications and discussions here at Todai-ji, Nara.

We appreciate very much the support of the technical and financial sponsors, and also thank the authors and participants, and all the committee members. Please enjoy Nara.



**Osami Wada**, *General Chair of EMC Compo 2013*

## *Program Overview:*

The technical program starts with a **Joint Workshop** together with **EDAPS 2013**, and we have three guest speakers, Prof. Madhavan Swaminathan from the Georgia Institute of Technology, Dr. Woong Hwan Ryu from Samsung Electronics, and Dr. William Wu Shen from TSMC. The topics cover Signal/Power/Thermal Integrity, high-performance mobile systems, and 3D IC design. An introduction to a new activity in Japan, the LPB interoperable design process working group (LPB-WG), will also be presented. LPB stands for the entire set of LSI, Packages and Boards, which will be co-designed for high-performance electronic systems.

After the Joint Workshop, EMC Compo 2013 will start with two **tutorials**, and a **Keynote Speech** by Dr. Toru Shimizu from Renesas Electronics. Forty eight **regular papers** in nine Regular Sessions, one Special Session, and a Poster Session including eleven poster presentations will follow. In the **Special Session**, "Tackling EMC in Real IC Chips", two guests, Prof. Jun Fan and Dr. Dian Yang, will give talks. A **workshop** on new EM noise evaluation methods with APD measurements will also be presented.